



SOT1916-1

FBGA609, fine-pitch ball grid array package; 609 terminals,
0.8 mm pitch, 21 mm x 21 mm x 2.37 mm body

26 June 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA609
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	04-06-2019
Manufacturer package code	98ASA01051D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	21	-	mm
package width	-	21	-	mm
seated height	-	2.37	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	609	-	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN FOOT AREA.
8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

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TITLE: FCPBGA, WITH LID, 21 X 21 X 2.37 PKG, 0.8 MM PITCH, 609 I/O INTERSTITIAL		DOCUMENT NO: 98ASA01051D	REV: C
		STANDARD: NON-JEDEC	
		SOT1916-1	04 JUN 2019

Figure 2. Package outline note FBGA609 (sot1916-1)

3 Legal information

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